



Material Content Data Sheet



Sales Product Name		ICE3GS03LJG		Issued		13. January 2016		
MA#		MA000820888						
Package		PG-DSO-8-42		Weight*		81.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.065	1.31	1.31	13060	13060
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.035	0.04		432	
	non noble metal	iron	7439-89-6	0.705	0.86		8643	
wire	non noble metal	copper	7440-50-8	28.624	35.09	36.00	350945	360128
	noble metal	gold	7440-57-5	0.171	0.21	0.21	2102	2102
	encapsulation	organic material	carbon black	1333-86-4	0.148	0.18		1819
plastics	plastics	epoxy resin	-	4.798	5.88		58822	
	inorganic material	silicondioxide	60676-86-0	44.514	54.60	60.66	545773	606414
leadfinish	non noble metal	tin	7440-31-5	0.824	1.01	1.01	10103	10103
plating	noble metal	silver	7440-22-4	0.084	0.10	0.10	1034	1034
glue	plastics	acrylic resin	-	0.117	0.14		1432	
	noble metal	silver	7440-22-4	0.467	0.57	0.71	5727	7159
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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